

Call for papers/ISAPP2019

International Symposium on Advanced Power Packaging

October 7&8, 2019

Suita Campus, Osaka University
Osaka, Japan

<http://www.isapp.jp/>

Abstract deadline: **May 31, 2019**

Scope

The 2019 International Symposium on Advanced Power Packaging (ISAPP2019) will be held from October 7th & 8th, at Osaka University, Osaka, Japan. This international symposium aims to gather and evaluate all the aspects of science, technology, and business in the fields of the next generation packaging technology and passive components of power electronics especially for wide band gap semiconductors (WBGs) and to review their reliability issues on power electronics applications including electric mobilities such as cars, trains, airplanes, industrial/humanoid robots, IoT, and renewable energies/energy grids. This symposium will bring together key persons from all over the world and from every sector of academy and industry in the field of next generation power electronics.

Main topics

· Packaging Materials

Solders, sinter joining, TLP joining, wiring, ceramic/organic substrates, molding/potting compounds, coating, TIM

· Process Technologies and Machines

Joining process and machine, wiring machine, molding machine, high-precision electronic printing, plating/coating, washing and surface treatment machine, drying/curing

· Passive components

Capacitors, resistors, soft-magnet and reactor

· Characterization, Design and Simulation

Thermal measurement, thermal management, cooling system, electric measurements, reliability test (power cycling, thermal shock, etc), corrosion tests, spectroscopy, design, life-time modeling

Technical Program

ISAPP2019 holds following sessions: plenary and invited lectures, approximately 30 invited talks, and 100 contributed papers at the poster sessions.

Abstract Submission

Contributed paper submissions should describe original and unpublished work related to power electronics packaging, passive components, and their reliability. At the online submission via the conference homepage, which will be open soon,

the authors are requested to choose one session where they prefer to give their presentations. Abstract is maximum 300 word long and extended abstract 4 pages maximum.

Important Dates

Abstract submission deadline	May 31, 2019
Notification of acceptance	June 28, 2019
Deadline for early registration	August 16, 2019
Extended abstract submission deadline	September 5, 2019

Organizing Committee (tentative)

Katsuaki Suganuma (Osaka Univ, Japan)
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Hiroshi Nishikawa (Osaka Univ, Japan)
Miyuki Harada (Kansai Univ, Japan)
Kiyoshi Hirao (AIST, Japan)
Junichi Murai (Mitsubishi Electric)
Takashi Nakamura (Osaka Univ, Japan)
Keiko Otsuka (ORIST, Japan)
Toshiro Sato (Shinshu Univ, Japan)
Keiji Toda (Toyota, Japan)
Kazuhiro Tsuruta (DENSO CORP, Japan)
Tetsuzo Ueda (Panasonic, Japan)
Kimihiro Yamanaka (Chukyo Univ, Japan)
Hiroshi Yamaguchi (AIST, Japan)

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Registration Fees

	Speaker	Early registration (Before August 16)	at ISAPP2019
Regular	30,000 JPY	30,000 JPY	50,000 JPY
Student	5,000 JPY	5,000 JPY	10,000 JPY

Point of Contact: ISAPP2019 office

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Venue

Icho Kaikan, Suita Campus, Osaka University
2-2 Yamadaoka, Suita, Osaka, Japan



Suita Campus map, Ichō Kaikan is building 11